

PCN Number:	20231130000.0	PCN Date:	December 04, 2023
Title:	Datasheet for LMC6482 and LMC649x		
Customer Contact:	Change Management team	Dept:	Quality Services
Change Type:	Electrical Specification		

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



LMC6482
SNOS674H – OCTOBER 1997 – REVISED NOVEMBER 2023

Changes from Revision G (April 2020) to Revision H (November 2023)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Deleted specifications are typical, high voltage gain, and power good output from <i>Features</i>	1
• Deleted M version device from data sheet; see the LMC6482QML for more information.....	1
• Updated front page figures in <i>Description</i>	1
• Updated <i>Pin Configuration and Functions</i>	2
• Added ± to input offset voltage, input offset voltage drift, input bias current, and input offset current in <i>Electrical Characteristics</i>	4
• Updated parameter names throughout <i>Electrical Characteristics</i> for consistency.....	4
• Deleted notes 1, 2, and 3 from <i>Electrical Characteristics</i>	4
• Changed supply current specification from total to per amplifier in <i>Electrical Characteristics</i>	4
• Deleted Figure 11 to 13, Figure 19 to 23, Figure 32 to 33, and Figure 47 to 52.....	8
• Updated functional block diagram.....	15
• Updated description of the input stage in <i>Amplifier Topology</i>	15
• Added Input Offset Voltage vs Common-Mode Voltage plot in <i>Amplifier Topology</i>	15
• Updated the description in <i>Rail-to-Rail Output</i>	16
• Added an improved instrumentation amplifier circuit to <i>Instrumentation Circuits</i>	18
• Added Figure 7-7, <i>Open-Loop Output Impedance</i> and related content to <i>Capacitive Load Compensation</i> ...	20
• Added OPA928 femtoampere-input bias-current op-amp recommendation to <i>Typical Single-Supply Applications</i>	23
• Deleted references to the library disk in <i>Spice Macromodel</i>	28

Changes from Revision D (March 2013) to Revision E (November 2023)	Page
• Updated <i>Features</i>	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Added the <i>Pin Configuration and Functions, Specifications, ESD Ratings, Thermal Information, Application and Implementation, Application Information, Typical Applications, Layout, Layout Guidelines, Device and Documentation Support, and Mechanical, Packaging, and Orderable Information</i> sections.....	1
• Deleted P (PDIP) packages from data sheet.....	1
• Changed application circuit in <i>Description</i>	1
• Moved ESD tolerance value from <i>Absolute Maximum Ratings</i> to <i>ESD Ratings</i>	4
• Updated note 1 of <i>Absolute Maximum Ratings</i>	4
• Changed <i>Operating Conditions</i> to <i>Recommended Operating Conditions</i> and deleted redundant table note....	4
• Moved thermal information values from <i>Operating Conditions</i> to <i>Thermal Information</i>	4
• Updated format of <i>Electrical Characteristics</i>	5
• Deleted table notes 1, 2, and 3 from <i>Electrical Characteristics</i> to be consistent with standard TI data sheets..	5
• Added \pm to input offset voltage, input offset voltage drift, input bias current, and input offset current in <i>Electrical Characteristics</i>	5
• Updated parameter names to be consistent with modern data sheets.....	5
• Moved the <i>AC Electrical Characteristics</i> and <i>DC Electrical Characteristics</i> to <i>Electrical Characteristics</i>	5
• Changed supply current specification from total to per amplifier in <i>Electrical Characteristics</i>	5
• Deleted Figures 13 to 15, Figures 21 to 25, Figures 34 to 35, and Figures 51 to 54.....	8
• Added Input Offset Voltage vs Common-Mode Voltage plot in <i>Amplifier Topology</i> and related description	14
• Updated description of <i>Rail-to-Rail Output</i>	15

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMC6482	SNOS674G	SNOS674H
LMC649x	SNOS724D	SNOS724E

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LMC6482>

<http://www.ti.com/product/LMC6492>

Reason for Change:

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150- millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200- mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device

Changes to product identification resulting from this PCN:

None.

Product Affected:

LMC6482AIM	LMC6482AIM/NOPB	LMC6482AIMX	LMC6482AIMX/NOPB
LMC6482AIN/NOPB	LMC6482IM	LMC6482IM/NOPB	LMC6482IMM
LMC6482IMM/NOPB	LMC6482IMMX	LMC6482IMMX/NOPB	LMC6482IMX

LMC6482IMX/NOPB	LMC6482IN/NOPB	LMC6492AEMX/NAK2	LMC6492AEMX/NOPB	
LMC6492BEMX/NOPB	LMC6494AEMX/NOPB	LMC6494BEMX/NOPB		

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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